

## ABSTRACT OF THE INVENTION

A metal support or leadframe for the bonding of electrical or optoelectronic components is provided. The  
5 leadframe includes a multiplicity of contact legs, that can respectively be connected to one end of a bonding wire for the bonding of a component at a bonding region. At least one electrically nonconducting structure is provided that mechanically interconnects at least two of  
10 the contact legs.